

RoHS

REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25

NOTE:
1.MATERIAL:
1.1.Housing: LCP UL94V-0 Black
1.2.Contact: Copper Alloy T=0.30
1.3.Shell: Copper Alloy T=0.20
2.PLATING:
2.1.Contact: Contact Area Gold Plated
Solder Area Sn Plated
Under Plated Nickel
2.2.Shell: Nickel Plated
3.SPECIFICATION:
3.1.Current: 1.5A
3.2.Voltage: 125V RMS
3.3.Withstanding Voltage: 500V AC
3.4.Contact Resistance: 30 mΩ max.
3.5.Insulation Resistance: 500 MΩ min.
3.6.Temperature Range: -20°C to +85°C

Part Number:
XF6038S-1188N X 5 B- 1 R

Electroplating:
0=FU金 1=1U金 2=2.5U金
3=3U金 4=6U金 5=15U金
6=30U金 7=50U金

Material:
1=PBT 2=PA46
3=PA66 4=PA9T 5=LCP

Colour:
B=黑色 G=绿色 R=红色 Y=黄色
V=紫色 W=白色 H=灰色 L=蓝色

environmental protection:
R=Rohs Free
H=Halogen Free

Packing:
1=Tray
2=Tape Reel

RECOMMENDED PCB LAYOUT(TOP VIEW)
TOLERANCE ±0.05

X.±0.50	X.°±	PART NO: XF6038S-1188N15B-1R	XFCN 兴飞连接器					
.X±0.25	.X°±							
.XX±0.15	.XX°±	TITLE: 沉板RJ45 板上8.6 柱高0.95	0769-82001899					
.XXX±0.10	.XXX°±		www.xfconn.com					
UNITS:	mm		DWG NO: /					
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN		APPD	Chen ZhiQiang		VIEW			
		CHKD	Liu Wei					
		DRAW	Chen HongJiang		SCALE	SHEET	REV	
		DATE	2024.12.02		NONE	1/1	A1	